

### **REMARKS**

With this Amendment, Claims 19, 20 and 24 are being currently amended. No Claims are being added or canceled. Claims 25 and 26 are renumbered according the comments in the Action. Thus, after entry of this Amendment, Claims 19-24 and 26-27 remain pending and under consideration. The amendments and various rejections of the claims will be addressed in detail, below.

#### **Amendments to the Claims:**

Claims 19, 20, and 24 are amended to recite the invention with greater clarity. In particular, the step of simultaneously transferring a processed and an unprocessed wafer is amended to read as “simultaneously transferring a processed and an unprocessed wafer from the process chamber to the respective loadlock chamber.” Support for this amendment can be found throughout the application, for example, in the Specification at pages 22-25 and FIGS. 16(a)-(i). Thus, Applicants submit that no new matter is introduced by the amendments.

#### **Rejections under 35 U.S.C. § 112**

Claims 19-24, 26 and 27 are rejected under 35 U.S.C. 112, first paragraph, as being allegedly failing to comply with the enablement requirement. In particular, the Examiner indicates that the step of “simultaneously transferring a processed and an unprocessed wafer between said loadlock chamber and said respective process chamber” is not described in the Specification in such a way to enable one of ordinary skill to make and use the invention. Applicants respectfully traverse.

Claims 19, 20 and 24 now recite “simultaneously transferring a processed and an unprocessed wafer from the process chamber to the respective loadlock chamber,” as suggested by the Examiner. Applicants submit that the invention recited in instant Claims 19, 20 and 24 are described in the Specification in a full and clear manner that enables one of ordinary skill in the art to make and use the invention. In particular, Applicants wish to draw the Examiner’s attention to the Specification at page 23, last paragraph, which describes that loadlock transfer arm 82 rotates into loadlock chamber 80, carrying both the first processed wafer A’ on lower wafer shelf 87 and the second unprocessed wafer B on upper wafer shelf 85. FIG. 16(e) also clearly illustrates that a processed wafer A’ and an unprocessed wafer B are simultaneously transferred from a process chamber to a respective loadlock chamber.

Therefore, Applicants respectfully request reconsideration of the rejection of Claims 19-24, 26 and 27 under 35 U.S.C. 112, first paragraph.

**Allowable Subject Matter:**

Applicants acknowledge with appreciation the Examiner's indication that Claim 23 contains allowable subject matter. In view of the amendments to base Claim 19, Claim 23 is now allowable.

Two U.S. patents are cited but not relied upon in the rejections. U.S. Patent No. 6,722,834 ("Tepman") teaches a robot blade with dual offset wafer support. U.S. Patent No. 5,810,549 ("Wytman") teaches a linear dual blade robot for transferring wafers. However, neither Tepman nor Wytman teach or suggest simultaneously transferring a processed and an unprocessed wafer from a process chamber to a loadlock chamber as recited in the instant Claims.

**CONCLUSION**

Applicants respectfully submit that the present application is now in condition for allowance, and a Notice of Allowance is respectfully requested. If any matters can be handled by telephone, Applicants request that the Examiner telephone Applicants' attorney at the number below. No fees beyond those being submitted concurrently herewith are believed due. However, the commissioner is authorized to charge any additional required fees, or credit any overpayment, to Dorsey & Whitney LLP Deposit Account No. 50-2319 (Order No. A-67736-1/MSS (463035-19)).

Respectfully submitted,

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